

Title (en)

CLAY-LIKE MOLDED BODY FOR FORMING NOBLE METAL SINTERED COMPACT

Title (de)

TONARTIGER FORMKÖRPER ZUR HERSTELLUNG EINES EDELMETALLSINTERKÖRPERS

Title (fr)

CORPS MOULÉ DE TYPE EN ARGILE PERMETTANT DE FORMER UN COMPACT FRITTÉ EN UN MÉTAL NOBLE

Publication

**EP 3075468 A4 20170802 (EN)**

Application

**EP 14865338 A 20141127**

Priority

- JP 2013246152 A 20131128
- JP 2014081317 W 20141127

Abstract (en)

[origin: EP3075468A1] A clay-like shaped body for forming a sintered precious metal body, the clay-like shaped body obtained by shaping a clay-like composition containing at least one powder selected from the group consisting of precious metal powders and precious metal alloy powders, an organic binder, an organic additive and water into either a wire-like shape having a diameter of 0.5 mm to 3.0 mm or a sheet-like shape having a thickness of 0.2 mm to 3.0 mm, wherein cracking does not occur when the clay-like shaped body is wound tightly once around the outer peripheral surface of a core rod having a circular cross-sectional shape with a diameter of 13 mm.

IPC 8 full level

**B22F 1/102** (2022.01); **B22F 1/103** (2022.01); **B22F 3/02** (2006.01); **B22F 9/00** (2006.01)

CPC (source: EP US)

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Citation (search report)

- [X] EP 0457350 A1 19911121 - MITSUBISHI MATERIALS CORP [JP]
- [A] US 3653884 A 19720404 - DAVIES IDWAL, et al
- See references of WO 2015080181A1

Designated contracting state (EPC)

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**EP 14865338 A 20141127**; JP 2013246152 A 20131128; JP 2014081317 W 20141127; US 201415037784 A 20141127